



Material Content Data Sheet



Sales Product Name		BGA 777N7 E6327		Issued		27. September 2017		
MA#		MA001067776						
Package		PG-TSNP-7-1		Weight*		3.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.147	3.81	3.81	38133	38133
leadframe	non noble metal	zinc	7440-66-6	0.004	0.11		1115	
	non noble metal	tin	7440-31-5	0.005	0.14		1394	
	non noble metal	chromium	7440-47-3	0.006	0.17		1672	
wire	non noble metal	copper	7440-50-8	2.136	55.32	55.74	553260	557441
	noble metal	gold	7440-57-5	0.038	0.97	0.97	9747	9747
encapsulation	organic material	carbon black	1333-86-4	0.006	0.16		1592	
	plastics	epoxy resin	-	0.178	4.62		46158	
	inorganic material	silicondioxide	60676-86-0	1.045	27.06	31.84	270584	318334
leadfinish	non noble metal	tin	7440-31-5	0.111	2.89	2.89	28876	28876
plating	noble metal	silver	7440-22-4	0.104	2.69	2.69	26878	26878
glue	plastics	epoxy resin	-	0.016	0.41		4118	
	noble metal	silver	7440-22-4	0.064	1.65	2.06	16473	20591
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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